

**PAT-NO:** JP02000230123A  
**DOCUMENT-IDENTIFIER:** JP 2000230123 A  
**TITLE:** RESIN ADDITIVE  
**PUBN-DATE:** August 22, 2000

**INVENTOR-INFORMATION:**

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**APPL-NO:** JP11031467  
**APPL-DATE:** February 9, 1999

**INT-CL (IPC):** C08L101/00 , C08K009/04 ,  
C08K009/06 , C08L067/02 ,  
C08L069/00

**ABSTRACT:**

PROBLEM TO BE SOLVED: To obtain a resin additive capable of controlling reduction in molecular weight in heating and melting a resin and preventing decrease in IZOD impact strength by subjecting an inorganic particle to a specific surface treatment.

SOLUTION: The surface of (A) an inorganic particle (preferably silica, alumina, their salts or glass) is treated with (B) catechin, then with (C) a saccharide (preferably sugar, a polysaccharide or their mixture) and further with (D) a coupling agent (preferably a silane-based coupling agent). Preferably, the component A subjected to the surface treatment with the component B is subjected to the surface treatment with the component C in an amount corresponding to 0.4-4.2 wt.% of the component A and the treated particle is subjected to surface treatment with the component D in an amount corresponding to 0.4-4.2 wt.% of the component A. Preferably, a resin to which the additive is added is a thermoplastic polyester-based resin or a thermoplastic resin containing the polyester-based resin.

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